Pch -100V -13A Power MOSFET

V _{DSS}	-100V
R _{DS(on)} (Max.)	200mΩ
I _D	±13A
P _D	20W

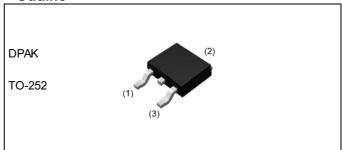
Features

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating; RoHS compliant

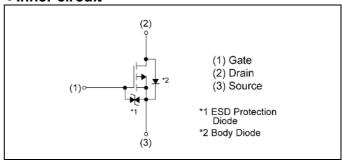
Application

Switching

Outline



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	16
Type	Basic ordering unit (pcs)	2500
	Taning and	TL
	Taping code	TL1
	Marking	RD3P130SP

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-100	V
Continuous drain current	I _D *1	±13	Α
Pulsed drain current	I _{DP} *2	±52	Α
Gate - Source voltage	V _{GSS}	±20	V
Power dissipation	P _D *3	20	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *3	-	ı	6.25	°C/W

● Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-100	-	-	V	
Breakdown voltage temperature coefficient $\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = -1 mA$		I _D = -1mA referenced to 25°C	-	-91.3	-	mV/°C	
Zero gate voltage drain current	I_{DSS} $V_{DS} = -100V, V_{GS} =$		-	-	-1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	-	1	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = -10V, I_{D} = -1mA$	-1.0	1	-2.5	V	
Gate threshold voltage temperature coefficient $\Delta V_{GS(t)}$		I _D = -1mA referenced to 25°C	-	3.0	-	mV/°C	
		V _{GS} = -10V, I _D = -6.5A	-	135	200		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = -4.5V, I _D = -6.5A	-	150	220	mΩ	
on state resistance		V _{GS} = -4.0V, I _D = -6.5A	-	155	230		
Gate resistance	R _G f = 1MHz, open drain		-	6.0	1	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = -10V, I _D = -13A	10	-	-	S	

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s , Duty cycle \leq 1%

^{*3} T_C=25°C

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C)

Daramatar	Cymahal	Conditions	Values			l leit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	2400	-	_	
Output capacitance	C _{oss}	V _{DS} = -25V	-	100	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	65	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -50V, V_{GS} = -10V$	-	20	-		
Rise time t_r^{*4}		I _D = -6.5A	-	25	-	no	
Turn - off delay time ${\mathsf t_{\mathsf d(off)}}^{\star 4}$		R _L ≃ 7.68Ω	-	70	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	60	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,				
Parameter	Symbol	Conditions	Values			l leit
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4	V _{DD} ≃ - 50V.	-	40	-	
Gate - Source charge	Q _{gs} *4	V _{DD} ≃ -50V, I _D = -13A, V _{GS} = -10V	-	6	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = -10V	-	6	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Symbol Conditions		Values			l leit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Continuous forward current	I _S *1	T = 25°C	-	-	-13	Α	
Pulse forward current	I _{SP} *2	T _a = 25°C	-	-	-52	Α	
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = -13A	-	-	-1.2	V	

Fig.1 Power Dissipation Derating Curve

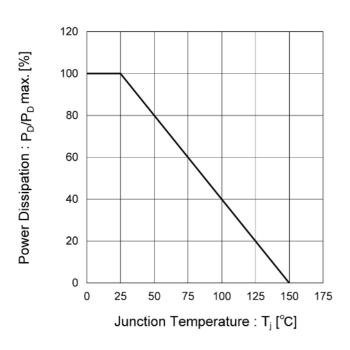


Fig.2 Maximum Safe Operating Area

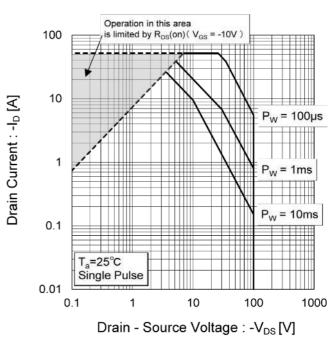


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

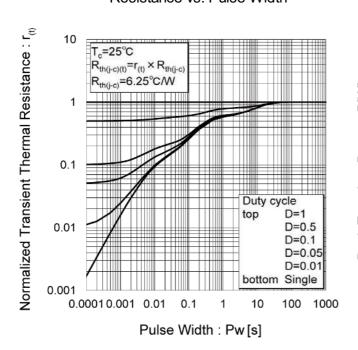


Fig.4 Single Pulse Maximum Power dissipation

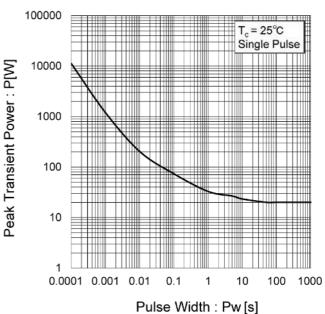


Fig.5 Typical Output Characteristics(I)

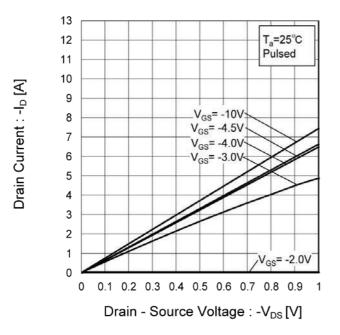
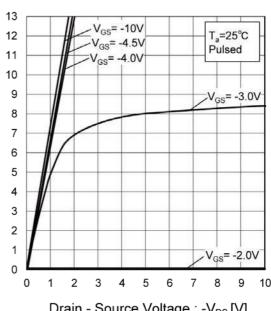


Fig.6 Typical Output Characteristics(II)



Drain Current : -I_D [A]

Drain - Source Voltage : -VDS [V]

Fig.7 Breakdown Voltage vs. **Junction Temperature**

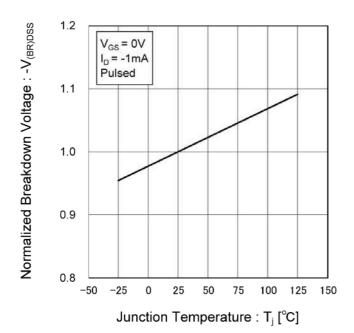


Fig.8 Typical Transfer Characteristics

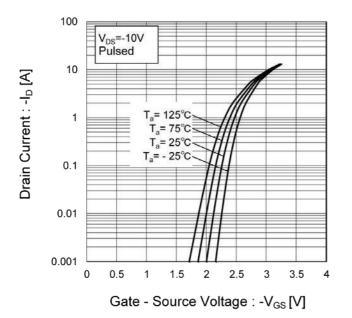


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

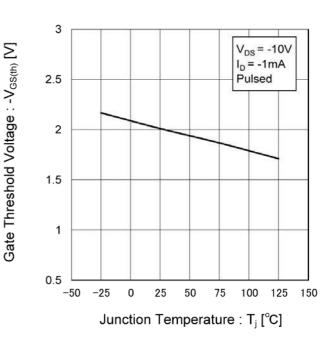
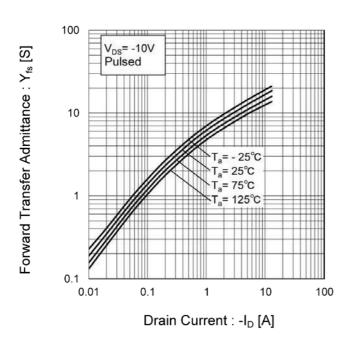


Fig.10 Forward Transfer Admittance vs.
Drain Current



6/12

Fig.11 Drain Current Derating Curve

120 100 **Drain Current Dissipation** 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

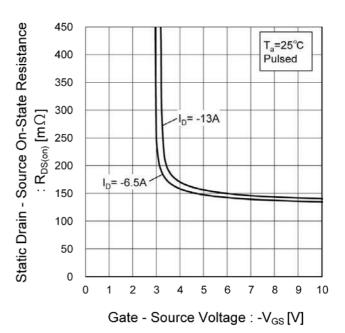
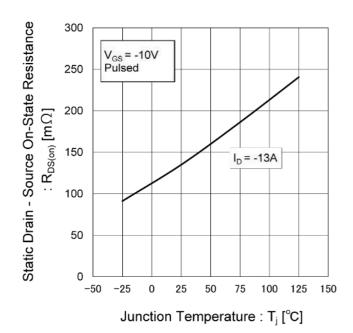


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



4/12

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

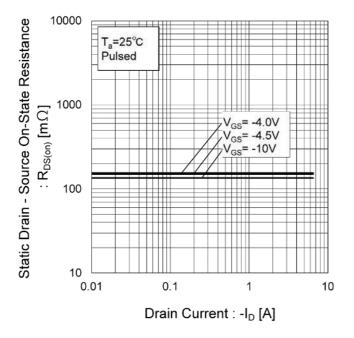


Fig.15 Static Drain - Source On - State
Resistance vs. Drain Current(II)

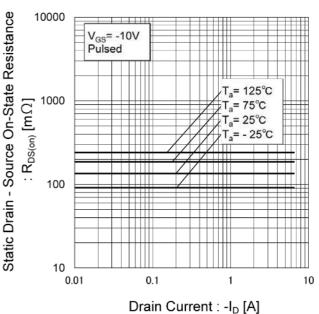


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

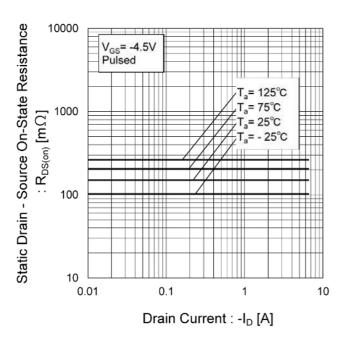


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

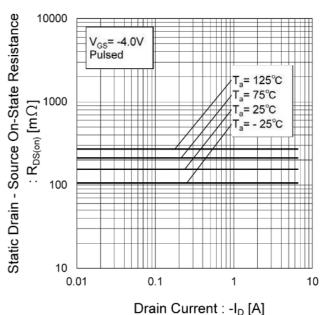


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

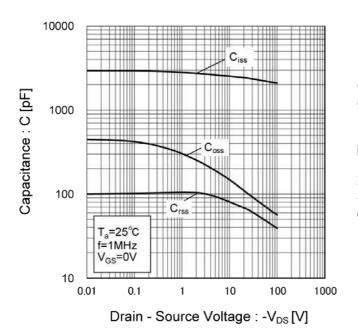


Fig.19 Switching Characteristics

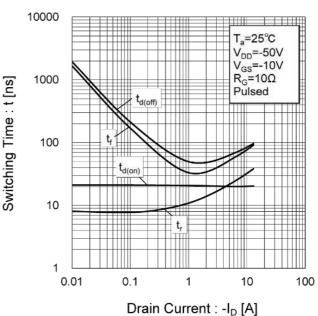


Fig.20 Dynamic Input Characteristics

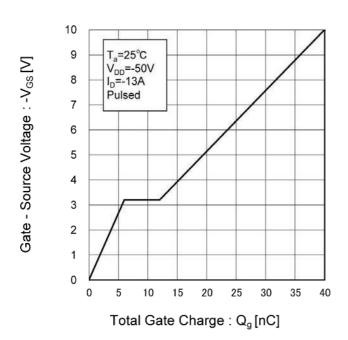
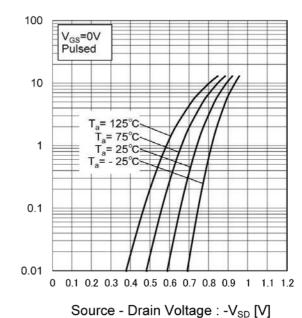


Fig.21 Source Current vs.

Source Drain Voltage



Source - Drain voitage . - vSD [v]

Source Current : -Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

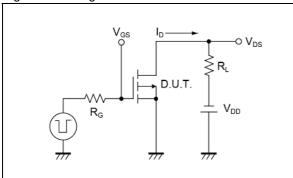


Fig.2-1 Gate Charge Measurement Circuit

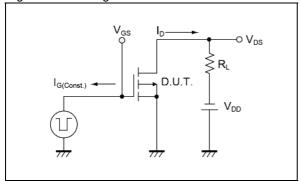


Fig.1-2 Switching Waveforms

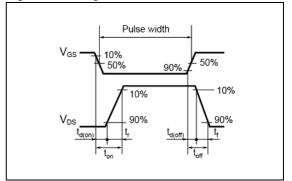
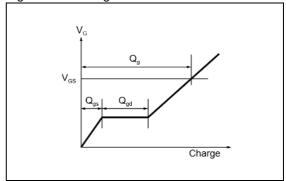
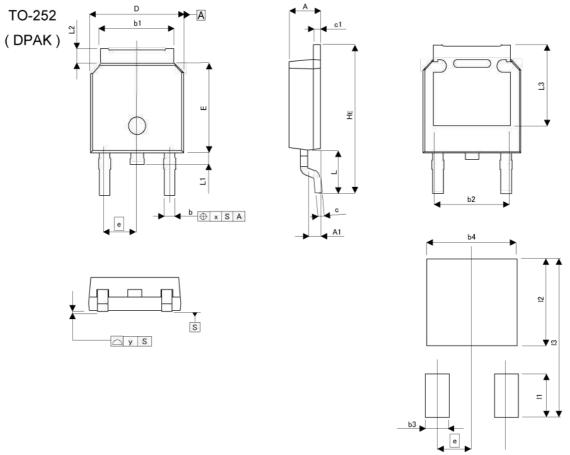


Fig.2-2 Gate Charge Waveform



ullet Dimensions (TL)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

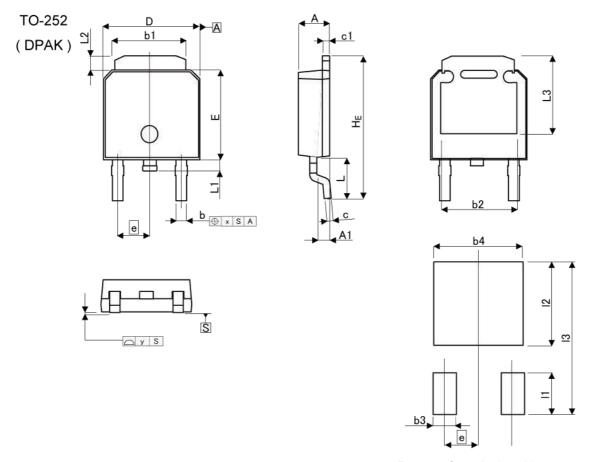
DIM -	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	.01
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	90	0.114	
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	:09
X	-	0.10		0.004
У	-	0.10		0.004

DIM	MILIM	ETERS	INC	HES
DIM L	MIN	MAX	MIN	MAX
b3	₽	1.10	028	0.043
b4	н.	5.40	S = s	0.213
I1	<u>#</u>	2.90	WEI	0.114
12	*	5.50	5.49	0.217
13	至	10.50	WES	0.413

Dimension in mm/inches



● Dimensions (TL1)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM -	MILIME	ETERS	INCHES	
ן ואוט	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	4.80		89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.30		0.091	
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.114	
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
х	*	0.25	(4)	0.010
у	76	0.10	(E)	0.004
- T	MILIME	ETERS	INCI	HES
DIM	MIN	MAX	MIN	MAX
b3	*	1.15	S#8	0.045
b4	-	5.55	950	0.219
11	E .	2.77	(4)	0.109
12	Wi Wi	5.50	25%	0.217
13	¥:	10.40	2000	0.409

Dimension in mm/inches



Notice

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Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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